SCLS347K - MAY 1996 - REVISED JULY 2003

- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17

description/ordering information

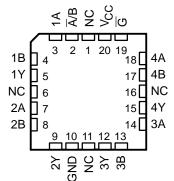
These quadruple 2-line to 1-line data selectors/multiplexers are designed for 4.5-V to 5.5-V V_{CC} operation.

The 'AHCT157 devices feature a common strobe (\overline{G}) input. When the strobe is high, all outputs are low. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. The devices provide true data.

SN54AHCT157 ... J OR W PACKAGE SN74AHCT157 ... D, DB, DGV, N, NS, OR PW PACKAGE (TOP VIEW)

	(101	vic,	
Ā/B 1A 1B 1Y 2A 2B 2Y GND	[] 2 [] 3	14 13 12 11] V _{CC}] G] 4A] 4B] 4Y] 3A] 3B] 3Y

SN54AHCT157 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AHCT157N	SN74AHCT157N
	SOIC - D	Tube	SN74AHCT157D	AHCT157
	3010 - 0	Tape and reel	SN74AHCT157DR	Anorisi
-40°C to 85°C	SOP – NS	Tape and reel	SN74AHCT157NSR	AHCT157
-40 C 10 85 C	SSOP – DB	Tape and reel	SN74AHCT157DBR	HB157
	TSSOP – PW	Tube	SN74AHCT157PW	HB157
	1330F - FW	Tape and reel	SN74AHCT157PWR	
	TVSOP – DGV	Tape and reel	SN74AHCT157DGVR	HB157
	CDIP – J	Tube	SNJ54AHCT157J	SNJ54AHCT157J
–55°C to 125°C	–55°C to 125°C CFP – W		SNJ54AHCT157W	SNJ54AHCT157W
	LCCC – FK	Tube	SNJ54AHCT157K	SNJ54AHCT157FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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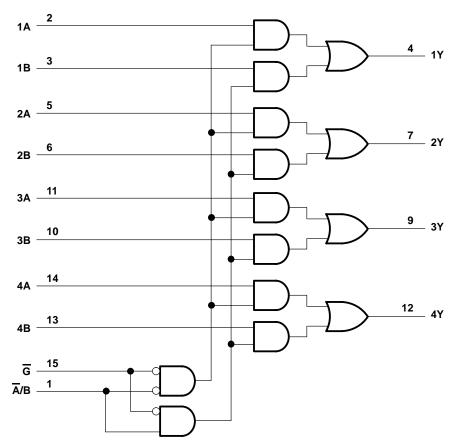


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SCLS347K - MAY 1996 - REVISED JULY 2003

	FUNCTION TABLE											
	INPU	OUTPUT										
G	Ā/B	Α	В	Y								
Н	Х	Х	Х	L								
L	L	L	х	L								
L	L	Н	х	Н								
L	Н	Х	L	L								
L	Н	Х	Н	Н								

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.



SCLS347K - MAY 1996 - REVISED JULY 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input voltage range, V _I (see Note 1) Output voltage range, V _O (see Note 1) Input clamp current, I _{IK} (V _I < 0) Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) Continuous output current, I _O (V _O = 0 to V _{CC}) . Continuous current through V _{CC} or GND Package thermal impedance, θ_{JA} (see Note 2): I	-0.5 V to 7 V -0.5 V to 7 V -0.5 V to 7 V -0.5 V to V _{CC} + 0.5 V -20 mA ±20 mA ±20 mA ±25 mA ±50 mA D package 73°C/W DB package 82°C/W DGV package 120°C/W N package 67°C/W NS package 64°C/W PW package 108°C/W

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54AHCT157		SN74AH	UNIT	
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	N	2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	5.5	0	5.5	V
Vo	Output voltage	0	Vcc	0	VCC	V
ЮН	High-level output current	DNG	-8		-8	mA
IOL	Low-level output current	201	8		8	mA
$\Delta t / \Delta v$	Input transition rise or fall time	9	20		20	ns/V
Т _А	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCLS347K - MAY 1996 - REVISED JULY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vcc	Τ,	λ = 25°C	;	SN54AH	CT157	SN74AHCT157		UNIT	
FARAWETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
N.	I _{OH} = -50 μA	4.5.1	4.4	4.5		4.4		4.4			
VOH	I _{OH} = -8 mA	4.5 V	3.94			3.8	Ņ	3.8		V	
Max	I _{OL} = 50 μA	4.5.1			0.1		0.1		0.1	V	
V _{OL}	I _{OL} = 8 mA	4.5 V			0.36		0.44		0.44	v	
lj	$V_{I} = 5.5 V \text{ or GND}$	0 V to 5.5 V			±0.1	4	±1*		±1	μA	
ICC	$V_{I} = V_{CC} \text{ or GND}, I_{O} = 0$	5.5 V			2	nc	20		20	μΑ	
∆lcc‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			1.35	Pho 04d	1.5		1.5	mA	
Ci	V _I = V _{CC} or GND	5 V		2	10				10	pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0$ V.

[†] This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	Тд	∖ = 25°C	;	SN54AH	ICT157	SN74AHCT157		UNIT	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
^t PLH	A or B	Y	Ci - 15 pE		4.1**	6.4**	1**	7.5**	1	7.5		
^t PHL	AUB	T	C _L = 15 pF		4.1**	6.4**	1**	7.5**	1	7.5	ns	
^t PLH	Ā/B	Y	C _L = 15 pF		5.3**	8.1**	1**	9.5**	1	9.5	ns	
^t PHL	A/B				5.3**	8.1**	1**	9.5**	1	9.5	9.5	
^t PLH	G	Y	C _I = 15 pF		5.6**	8.6**	1**	10**	1	10	ns	
^t PHL	G	Y			5.6**	8.6**	1**	10**	1	10	115	
^t PLH	A or B	Y	C _I = 50 pF		5.6	8.7	0	10.8	1	9.8	ns	
^t PHL	AUB		CL = 30 pr		5.6	8.7	20	10.8	1	9.8	115	
^t PLH	Ā/B	Y	$C_{\rm L} = 50 \rm pF$		6.8	10.4	<i>x</i> 1	13.2	1	12	-	
^t PLH	A/B	r r	C _L = 50 pF		6.8	10.4	1	13.2	1	12	ns	
^t PLH	G	Y	$C_{1} = 50 \text{ pF}$		7.1	11	1	13.5	1	12		
^t PHL	G	r r	C _L = 50 pF		7.1	11	1	13.5	1	12	ns	

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	SN7	UNIT		
	FARAMETER	SN74AHCT157 MIN TYP MAX 0.4 0.8 -0.4 -0.8 4.8 2			
VOL(P)	Quiet output, maximum dynamic V _{OL}		0.4	0.8	V
VOL(V)	Quiet output, minimum dynamic V _{OL}		-0.4	-0.8	V
VOH(V)	Quiet output, minimum dynamic V _{OH}		4.8		V
V _{IH(D)}	High-level dynamic input voltage	2			V
V _{IL(D)}	Low-level dynamic input voltage			0.8	V

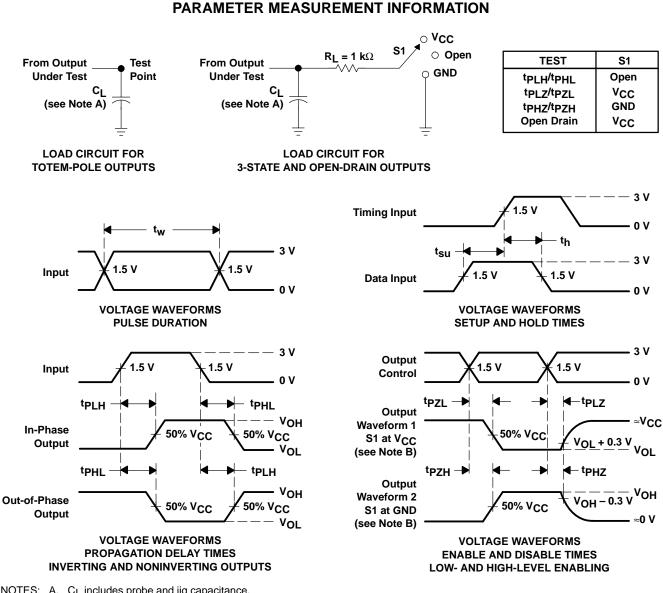
NOTE 4: Characteristics are for surface-mount packages only.

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SCLS347K - MAY 1996 - REVISED JULY 2003

ope	operating characteristics, V _{CC} = 5 V, T _A = 25°C									
	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT					
Cpd	Power dissipation capacitance	No load,	f = 1 MHz	11	pF					



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_Q = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHCT157D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DBLE	OBSOLETE	SSOP	DB	16		TBD	Call TI	Call TI
SN74AHCT157DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DGVRG4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHCT157NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHCT157NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWLE	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI
SN74AHCT157PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

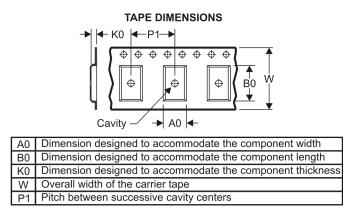
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

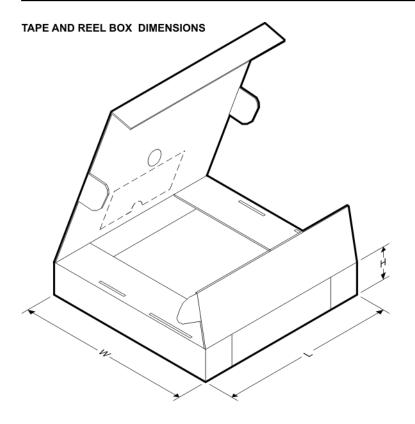


Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT157DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74AHCT157DGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHCT157DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHCT157NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHCT157PWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT157DBR	SSOP	DB	16	2000	346.0	346.0	33.0
SN74AHCT157DGVR	TVSOP	DGV	16	2000	346.0	346.0	29.0
SN74AHCT157DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AHCT157NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74AHCT157PWR	TSSOP	PW	16	2000	346.0	346.0	29.0

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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